

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die	Doped Silicon	Silicon (Si)	7440-21-3	0.82928	100.0	11.91217
			<b>Subtotal</b>	<b>0.82928</b>	<b>100</b>	<b>11.91217</b>
Post-plating	Pure Metal	Tin (Sn)	7440-31-5	1.74041	100.0	25
			<b>Subtotal</b>	<b>1.74041</b>	<b>100</b>	<b>25</b>
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.02314	0.04	0.3324
	Copper alloy	Iron (Fe)	7439-89-6	0.05785	0.1	0.831
	Copper alloy	Copper (Cu)	7440-50-8	57.77037	99.86	829.8366
			<b>Subtotal</b>	<b>57.85136</b>	<b>100</b>	<b>831</b>
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	3.40686	8.7	48.9375
	Polymer	Epichlorohydrin/Diethyleneglycol Epoxy resin (generic)	25928-94-3	6.26549	16.0	90
	Filler	Silica fused	60676-86-0	29.36949	75.0	421.875
	Carbon Black	Carbon black	1333-86-4	0.11748	0.3	1.6875
			<b>Subtotal</b>	<b>39.15932</b>	<b>100</b>	<b>562.5</b>
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.32024	100.0	4.6
			<b>Subtotal</b>	<b>0.32024</b>	<b>100</b>	<b>4.6</b>
Die Attach	Lead alloy	Tin (Sn)	7440-31-5	0.00497	5.0	0.07138
	Lead alloy	Silver (Ag)	7440-22-4	0.00248	2.5	0.03569
	Lead alloy	Lead (Pb)	7439-92-1	0.09194	92.5	1.3206
			<b>Subtotal</b>	<b>0.09939</b>	<b>100</b>	<b>1.42767</b>
			<b>Total</b>	<b>100</b>	<b>100</b>	<b>1436.43984</b>

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